503297460 05/07/2015

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
JINQUAN XU	04/14/2014

## **RECEIVING PARTY DATA**

Name:	UNITED TECHNOLOGIES CORPORATION	
Street Address:	1 FINANCIAL PLAZA	
City:	HARTFORD	
State/Country:	CONNECTICUT	
Postal Code:	06101	

#### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	14706659

#### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:	RICHARD D. GETZ	
SIGNATURE:	/rdg/	
DATE SIGNED:	05/07/2015	

#### **Total Attachments: 2**

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PATENT 503297460 REEL: 035589 FRAME: 0822

### **ASSIGNMENT**

#### THIS INSTRUMENT OF ASSIGNMENT WITNESSETH THAT:

WHEREAS, I, JinQuan Xu, resident of 30 Frederick T. Miller Way, East Greenwich, RI 02818 have invented improvements in

# METHOD FOR FORMING COMPONENTS USING ADDITIVE MANUFACTURING AND RE-MELT

for which we executed an application for United States Letters Patent on even date herewith; and

WHEREAS, United Technologies Corporation, a Delaware corporation, having a place of business at 1 Financial Plaza, Hartford, CT 06101, is desirous of acquiring an interest in said invention, said application and the Letters Patent to be issued therefor;

NOW, THEREFORE, to all whom it may concern, be it known that for and in consideration of the sum of ONE DOLLAR to each in hand paid and other good and valuable consideration, the receipt whereof is hereby acknowledged, we have sold, assigned and set over, and do hereby sell, assign and set over to said corporation, its successors or assigns, the entire right, title and interest to and in said invention in the United States and in all countries foreign to the United States, said United States application for Letters Patent therefor and in any non-provisional application that may claim said invention or priority to said application, and any divisional, continuation, and/or continuation-in-part thereof, and the Letters Patent when issued; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue the Letters Patent based upon said application to said corporation as the assignees of our entire right, title and interest to and in the same, for the sole use and behoof of said corporation, its successors or assigns.

And we also hereby covenant and agree to sign all proper papers including divisional and other applications for patents and assignments thereof in the United States and application for patents and assignments in all countries foreign to the United States, and to

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PATENT REEL: 035589 FRAME: 0823 execute all rightful oaths and to take any other proper action that may in the judgment of the said corporation be necessary for securing thereto full rights to said invention, all of the foregoing to be at the expense of said corporation.

IN TESTIMONY WHEREOF, I have hereunto set my hand this

J

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Witness: